

N-Ch 100V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

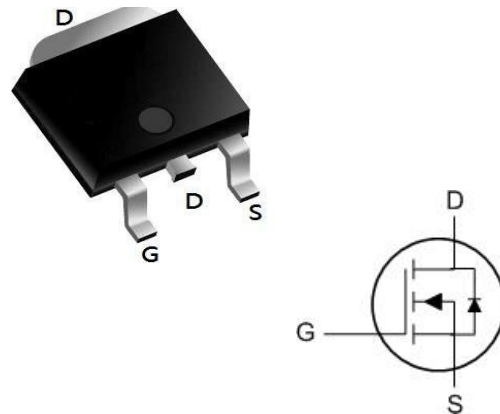
BVDSS	RDSON	ID
100V	18 mΩ	50A

Description

The SM2910 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The SM2910 meets the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter	Max.	Units
V _{DSS}	Drain-Source Voltage	100	V
V _{GSS}	Gate-Source Voltage	±20	V
I _D	Continuous Drain Current	T _C = 25°C	50
		T _C = 100°C	30
I _{DM}	Pulsed Drain Current ^{note1}	150	A
EAS	Single Pulsed Avalanche Energy ^{note2}	62.6	mJ
P _D	Power Dissipation	73	W
R _{θJC}	Thermal Resistance, Junction to Case	2.0	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +175	°C

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	100	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance <small>note2</small>	V _{GS} =10V, I _D =20A	-	18	28	mΩ
		V _{GS} =4.5V, I _D =10A	-	22	32	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	3727	-	pF
C _{oss}			-	180	-	pF
C _{rss}	Reverse Transfer Capacitance		-	148	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =15A, V _{GS} =10V	-	40	-	nC
Q _{gs}	Gate-Source Charge		-	6.2	-	nC
Q _{gd}	Gate-Drain("Miller") Charge		-	28	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =30V, I _D =15A, R _G =1.8Ω, V _{GS} =10V	-	22	-	ns
t _r	Turn-on Rise Time		-	182	-	ns
t _{d(off)}	Turn-off Delay Time		-	80	-	ns
t _f	Turn-off Fall Time		-	142	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	150	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	IF=30A, dI/dt=100A/μs	-	71	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	145	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T_J=25°C, V_{DD}=50V, V_G=10V, L=0.5mH, R_g=25Ω, I_{AS}=14.5A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure 1: Output Characteristics

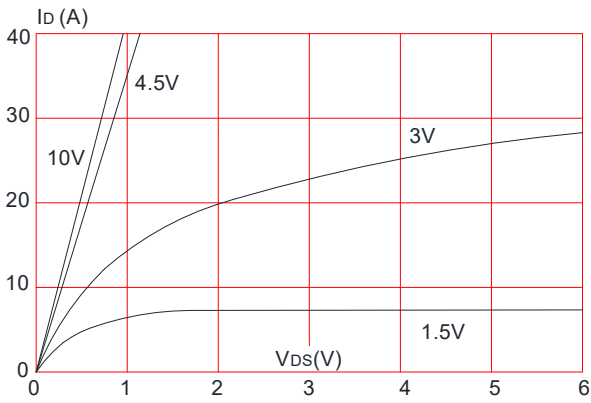


Figure 2: Typical Transfer Characteristics

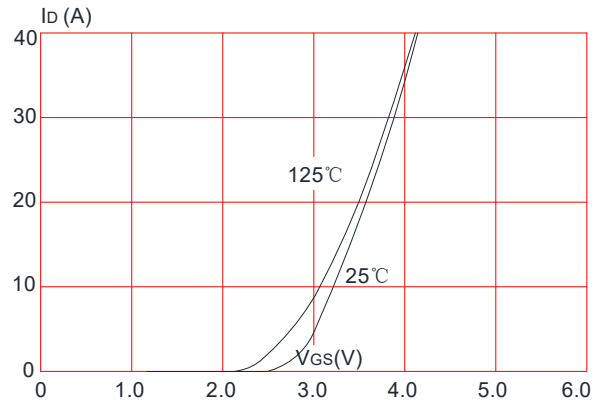


Figure 3: On-resistance vs. Drain Current

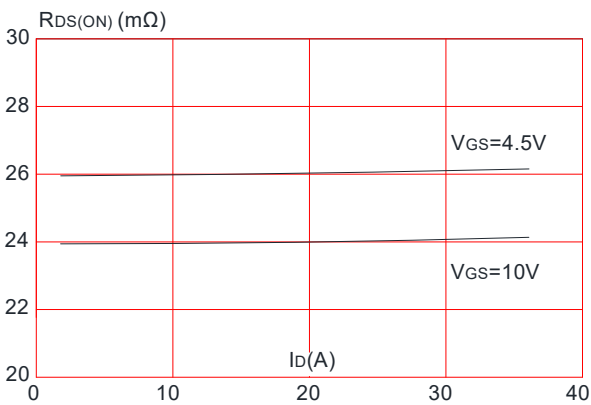


Figure 4: Body Diode Characteristics

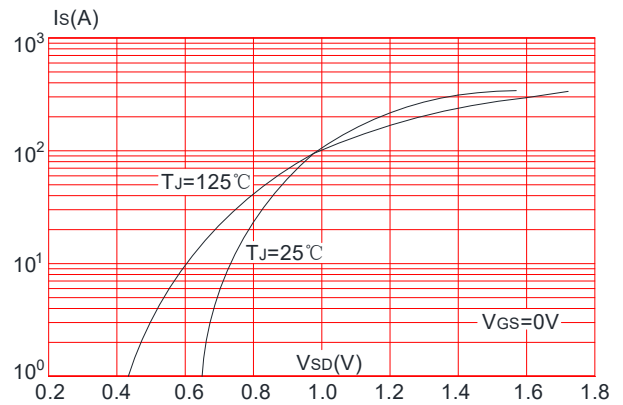


Figure 5: Gate Charge Characteristics

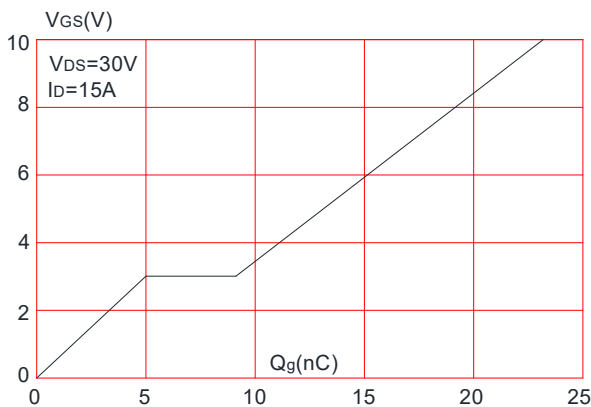


Figure 6: Capacitance Characteristics

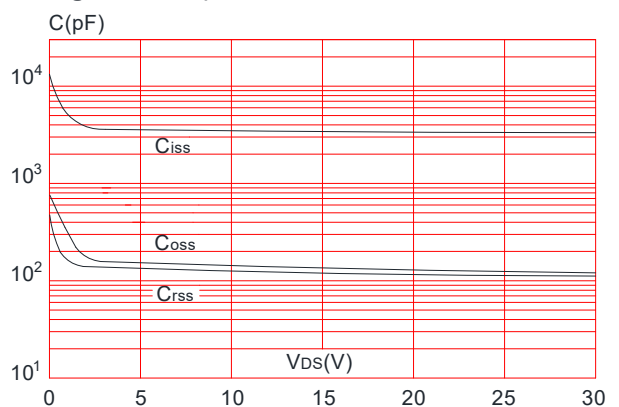


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

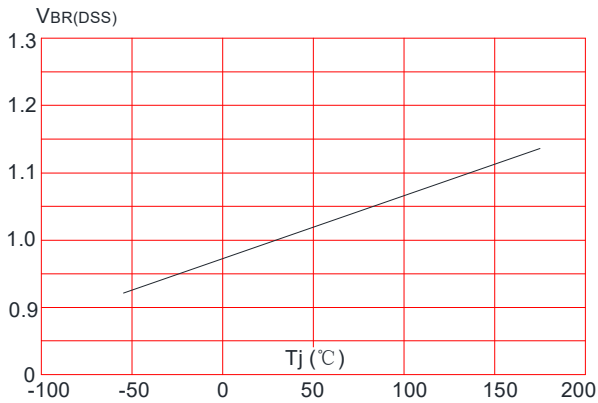


Figure 8: Normalized on Resistance vs. Junction Temperature

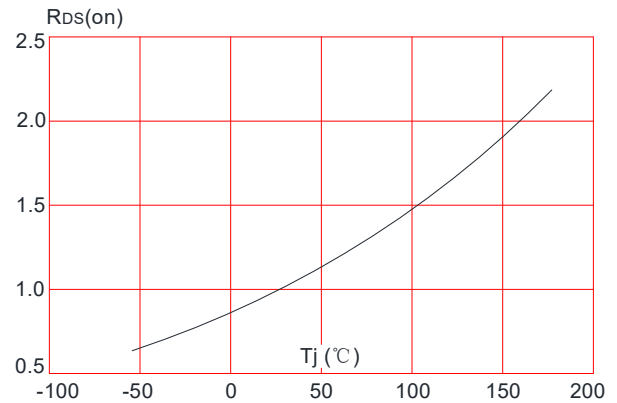


Figure 9: Maximum Safe Operating Area

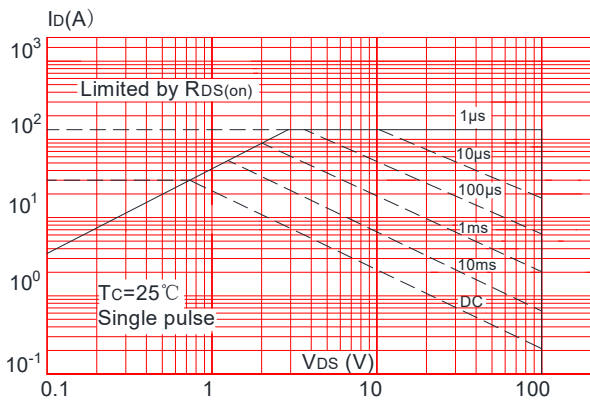


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

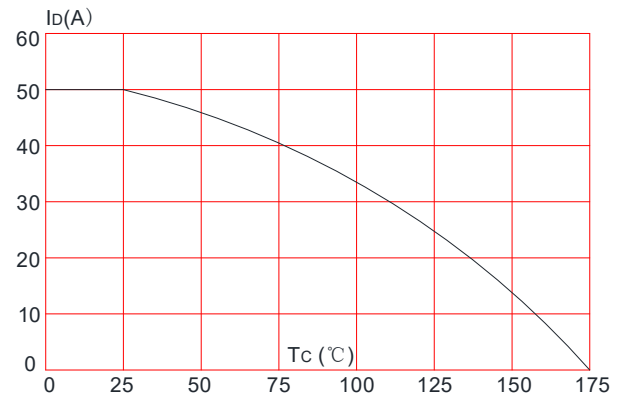
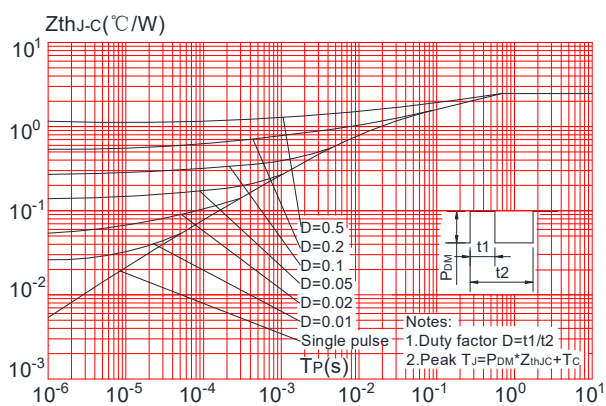
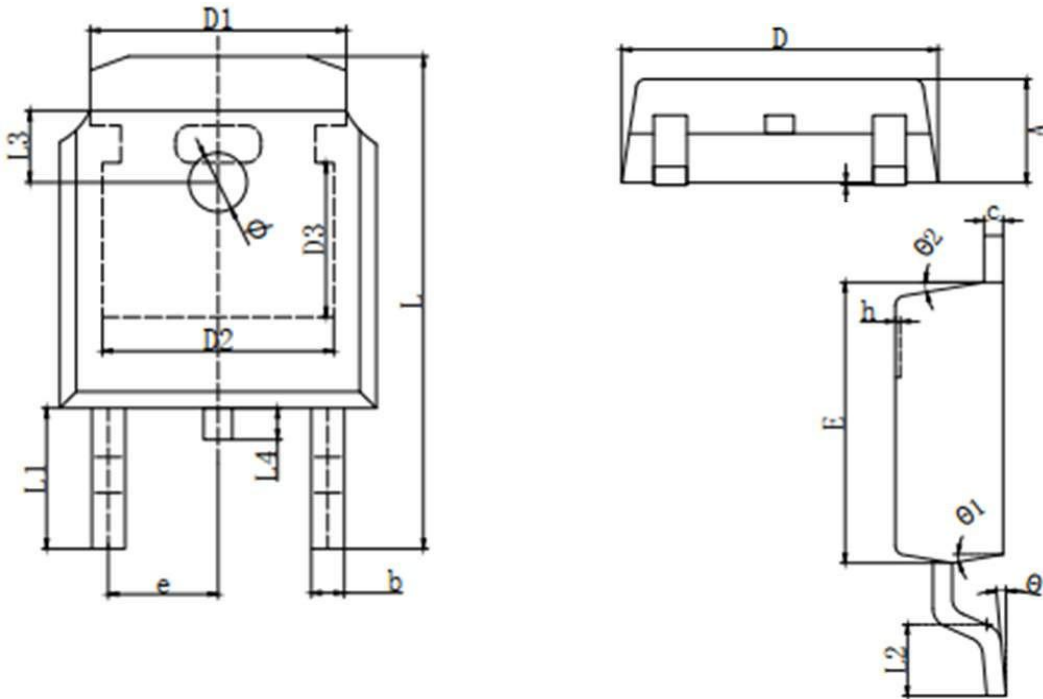


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-252 Package outline



SYMBOL	MILLIMETER		SYMBOL	MILLIMETER	
	MIN	MAX		MIN	MAX
A	2.200	2.400	h	0.000	0.200
A1	0.000	0.127	L	9.900	10.30
b	0.640	0.740	L1	2.888 REF	
c	0.460	0.580	L2	1.400	1.700
D	6.500	6.700	L3	1.600 REF	
D1	5.334 REF		L4	0.600	1.000
D2	4.826 REF		ϕ	1.100	1.300
D3	3.166 REF		θ	0°	8°
E	6.000	6.200	$\theta 1$	9° TYP2	
e	2.286 TYP		$\theta 2$	9° TYP	